



Material Content Data Sheet



Sales Product Name		IPD075N03L G		Issued		25. September 2017		
MA#		MA000598096						
Package		PG-TO252-3-311		Weight*		316.67 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.899	0.28	0.28	2839	2839
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		136	
	non noble metal	iron	7439-89-6	0.143	0.05		452	
	non noble metal	copper	7440-50-8	143.098	45.19	45.25	451879	452467
	non noble metal	aluminium	7429-90-5	2.132	0.67	0.67	6732	6732
wire	non noble metal	aluminium	7429-90-5	2.132	0.67	0.67	6732	6732
encapsulation	organic material	carbon black	1333-86-4	0.322	0.10		1015	
	plastics	epoxy resin	-	19.410	6.13		61295	
	inorganic material	silicondioxide	60676-86-0	126.431	39.92	46.15	399247	461557
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11810	11810
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	273	274
solder	non noble metal	tin	7440-31-5	0.023	0.01		74	
	noble metal	silver	7440-22-4	0.029	0.01		92	
	non noble metal	lead	7439-92-1	1.114	0.35	0.37	3517	3683
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	iron	7439-89-6	0.019	0.01		61	
	non noble metal	copper	7440-50-8	19.177	6.06	6.07	60559	60638
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com